

Fast Recovery Diodes (Hockey PUK Version), 375 A



DO-200AB (B-PUK)

FEATURES

- High power FAST recovery diode series
- 4.5 μ s recovery time
- High voltage ratings up to 4500 V
- High current capability
- Optimized turn-on and turn-off characteristics
- Low forward recovery
- Fast and soft reverse recovery
- Press PUK encapsulation
- Case style conform to JEDEC® DO-200AB (B-PUK)
- Maximum junction temperature 125 °C
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912


RoHS
COMPLIANT

PRODUCT SUMMARY

$I_{F(AV)}$	375 A
Package	B-PUK (DO-200AB)
Circuit configuration	Single Diode

TYPICAL APPLICATIONS

- Snubber diode for GTO
- High voltage freewheeling diode
- Fast recovery rectifier applications

MAJOR RATINGS AND CHARACTERISTICS

PARAMETER	TEST CONDITIONS	VALUES	UNITS
$I_{F(AV)}$		375	A
	T_{hs}	55	°C
$I_{F(RMS)}$		408	A
I_{FSM}	50 Hz	5500	
	60 Hz	5760	
V_{RRM}	Range	3000 to 4500	V
t_{rr}		4.5	μ s
	T_J	125	°C
T_J		-40 to 125	

ELECTRICAL SPECIFICATIONS

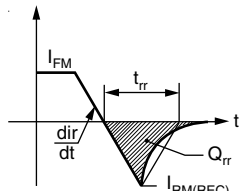
VOLTAGE RATINGS

TYPE NUMBER	VOLTAGE CODE	V_{RRM} , MAXIMUM REPETITIVE PEAK REVERSE VOLTAGE V	V_{RSM} , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I_{RRM} MAXIMUM AT $T_J = T_J$ MAXIMUM mA
VS-SD263C..S50L	30	3000	3100	50
	36	3600	3700	
	40	4000	4100	
	45	4500	4600	

**FORWARD CONDUCTION**

PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum average forward current at heatsink temperature	$I_{F(AV)}$	180° conduction, half sine wave Double side (single side) cooled		375 (150)	A
Maximum RMS forward current	$I_{F(RMS)}$	25 °C heatsink temperature double side cooled		725	°C
Maximum peak, one-cycle forward, non-repetitive surge current	I_{FSM}	t = 10 ms	No voltage reapplied	5500	A
		t = 8.3 ms	No voltage reapplied	5760	
		t = 10 ms	50 % V_{RRM} reapplied	4630	
		t = 8.3 ms	50 % V_{RRM} reapplied	4850	
Maximum I^2t for fusing	I^2t	t = 10 ms	No voltage reapplied	151	kA ² s
		t = 8.3 ms	No voltage reapplied	138	
		t = 10 ms	50 % V_{RRM} reapplied	107	
		t = 8.3 ms	50 % V_{RRM} reapplied	98	
Maximum $I^2\sqrt{t}$ for fusing	$I^2\sqrt{t}$	t = 0.1 to 10 ms, no voltage reapplied		1510	kA ² √s
Low level value of threshold voltage	$V_{F(TO)1}$	(16.7 % $\times \pi \times I_{F(AV)} < I < \pi \times I_{F(AV)}$, $T_J = T_J$ maximum)		1.56	V
High level value of threshold voltage	$V_{F(TO)2}$	(I > $\pi \times I_{F(AV)}$, $T_J = T_J$ maximum)		1.71	
Low level value of forward slope resistance	r_{f1}	(16.7 % $\times \pi \times I_{F(AV)} < I < \pi \times I_{F(AV)}$, $T_J = T_J$ maximum)		1.64	mW
High level value of forward slope resistance	r_{f2}	(I > $\pi \times I_{F(AV)}$, $T_J = T_J$ maximum)		1.53	
Maximum forward voltage drop	V_{FM}	$I_{pk} = 1000$ A, $T_J = T_J$ maximum, $t_p = 10$ ms sinusoidal wave		3.20	V

RECOVERY CHARACTERISTICS

CODE	MAXIMUM VALUE AT $T_J = 25$ °C	TEST CONDITIONS			TYPICAL VALUES AT $T_J = 150$ °C			
	t_{rr} AT 25 % I_{RRM} (μs)	I_{pk} SQUARE PULSE (A)	dI/dt ⁽¹⁾ (A/μs)	V_r (V)	t_{rr} AT 25 % I_{RRM} (μs)	Q_{rr} (μC)	I_{rr} (A)	
S50	5.0	1000	100	- 50	4.5	680	240	

Note(1) $dI/dt = 25$ A/μs, $T_J = 25$ °C**THERMAL AND MECHANICAL SPECIFICATIONS**

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction operating temperature range	T_J		- 40 to 125	°C
Maximum storage temperature range	T_{Stg}		- 40 to 150	
Maximum thermal resistance, junction to heatsink	R_{thJ-hs}	DC operation single side cooled	0.11	K/W
		DC operation double side cooled	0.05	
Mounting force, ± 10 %			9800 (1000)	N (kg)
Approximate weight			230	g
Case style		See dimensions - link at the end of datasheet	DO-200AB (B-PUK)	

 ΔR_{thJ-hs} CONDUCTION

CONDUCTION ANGLE	SINUSOIDAL CONDUCTION		RECTANGULAR CONDUCTION		TEST CONDITIONS	UNITS
	SINGLE SIDE	DOUBLE SIDE	SINGLE SIDE	DOUBLE SIDE		
180°	0.012	0.011	0.008	0.008	$T_J = T_J$ maximum	K/W
120°	0.014	0.015	0.014	0.014		
90°	0.018	0.018	0.019	0.019		
60°	0.026	0.027	0.027	0.028		
30°	0.045	0.046	0.046	0.046		

Note

- The table above shows the increment of thermal resistance R_{thJ-hs} when devices operate at different conduction angles than DC

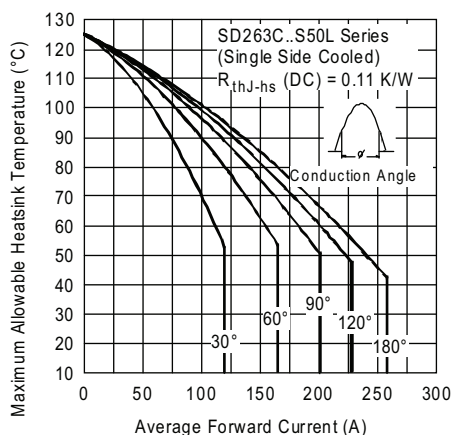


Fig. 1 - Current Ratings Characteristics

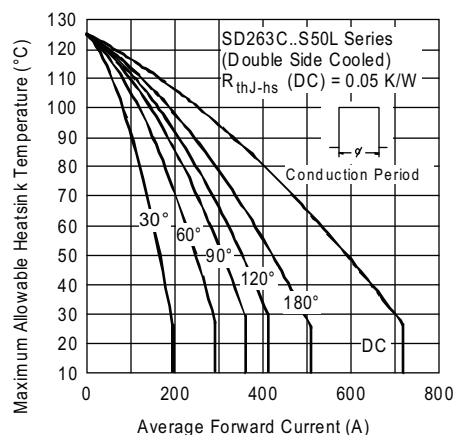


Fig. 4 - Current Ratings Characteristics

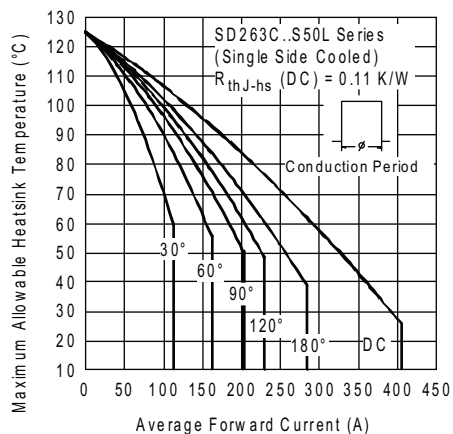


Fig. 2 - Current Ratings Characteristics

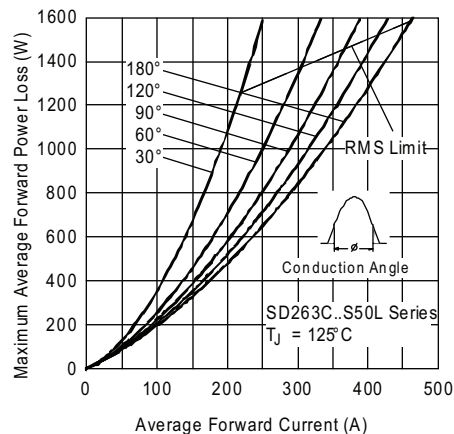


Fig. 5 - Forward Power Loss Characteristics

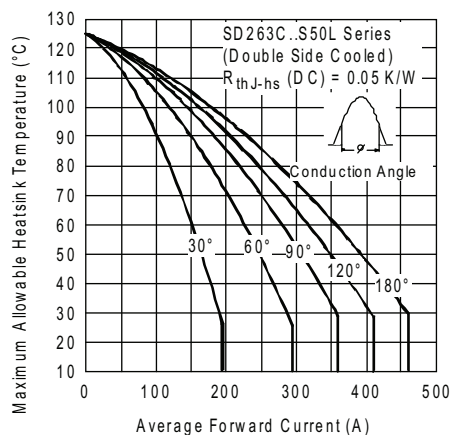


Fig. 3 - Current Ratings Characteristics

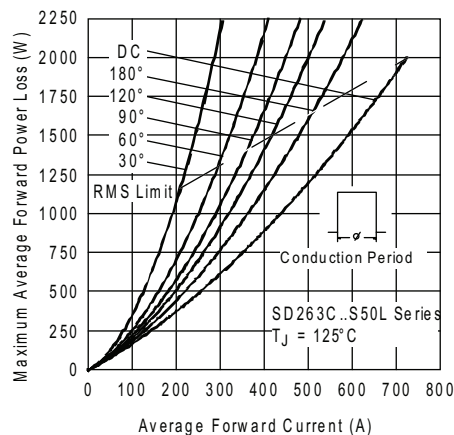


Fig. 6 - Forward Power Loss Characteristics

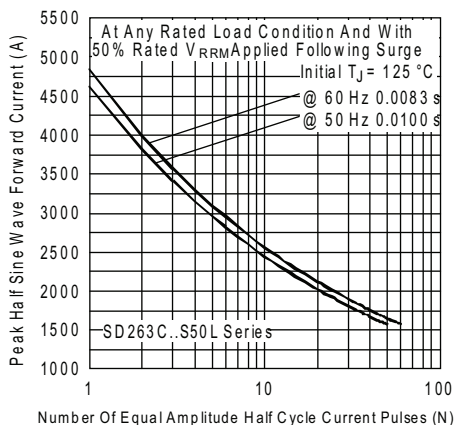


Fig. 7 - Maximum Non-Repetitive Surge Current Single and Double Side Cooled

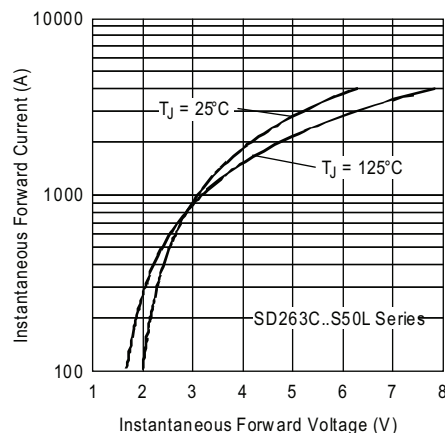


Fig. 9 - Forward Voltage Drop Characteristics

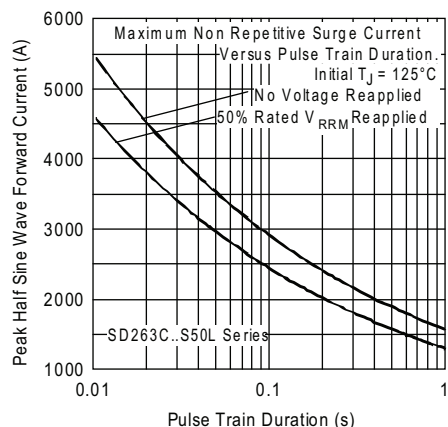


Fig. 8 - Maximum Non-Repetitive Surge Current Single and Double Side Cooled

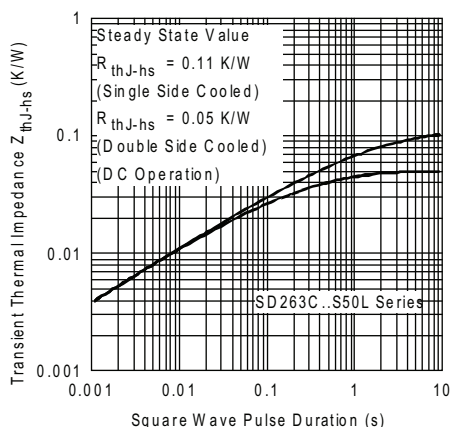


Fig. 10 - Thermal Impedance Z_{thJ-hs} Characteristic

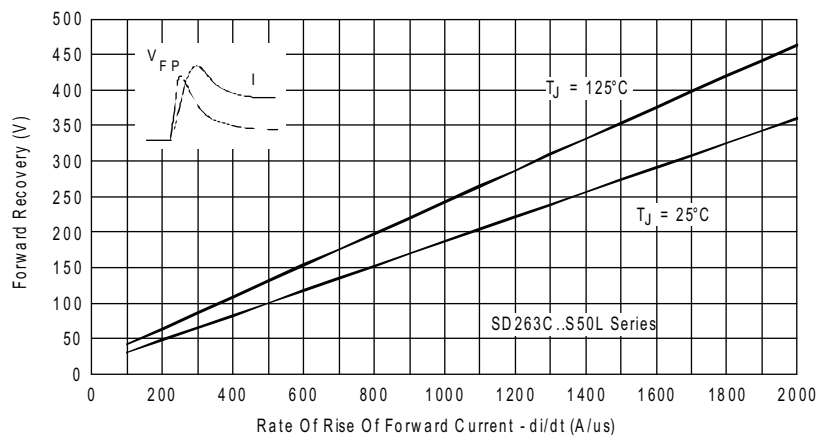


Fig. 11 - Typical Forward Recovery Characteristics

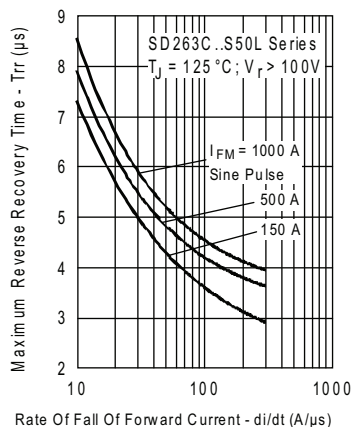


Fig. 12 - Recovery Time Characteristics

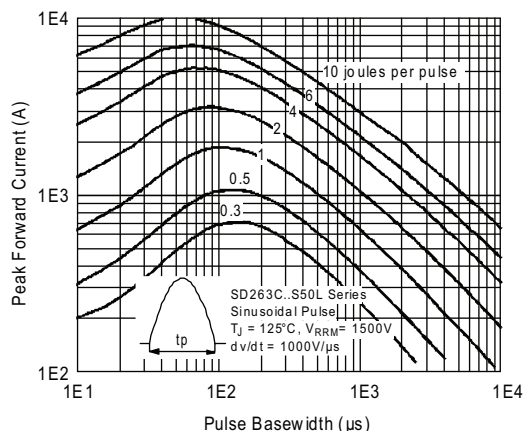


Fig. 15 - Maximum Total Energy Loss Per Pulse Characteristics

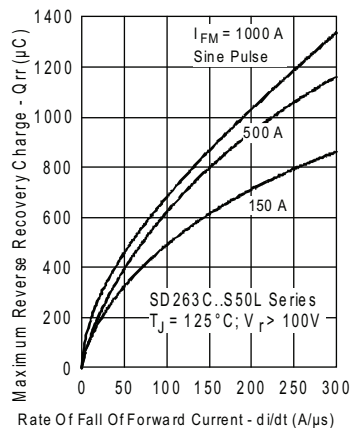


Fig. 13 - Recovery Charge Characteristics

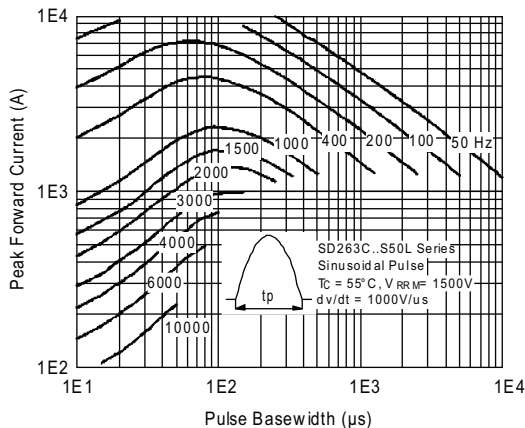


Fig. 16 - Frequency Characteristics

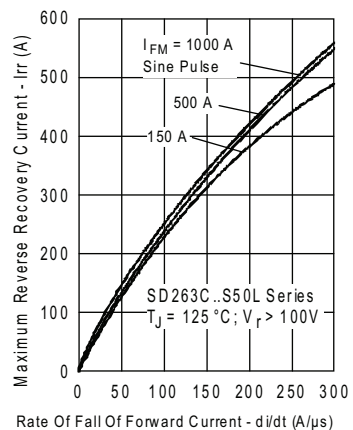


Fig. 14 - Recovery Current Characteristics

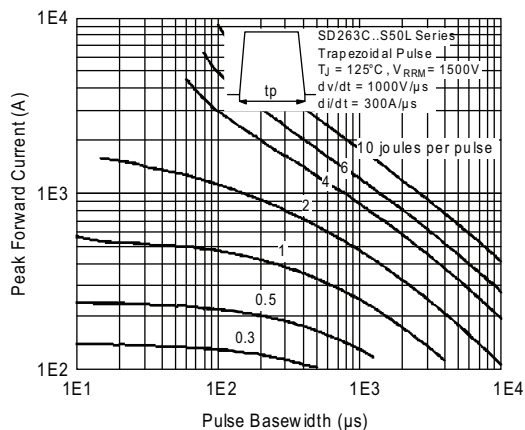


Fig. 17 - Maximum Total Energy Loss Per Pulse Characteristics

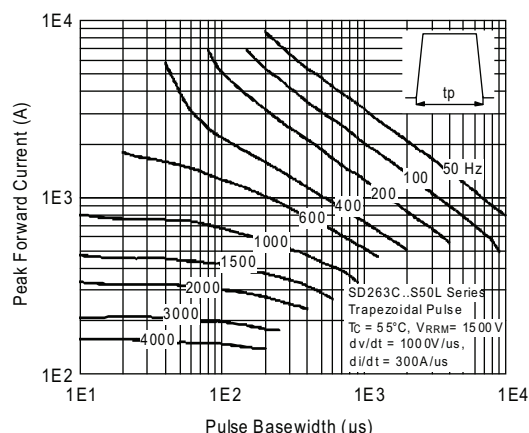


Fig. 18 - Frequency Characteristics

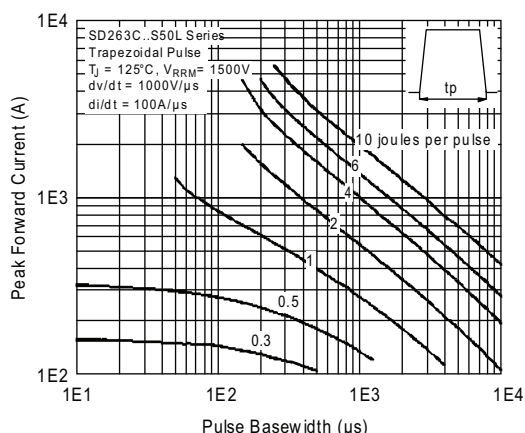


Fig. 19 - Maximum Total Energy Loss Per Pulse Characteristics

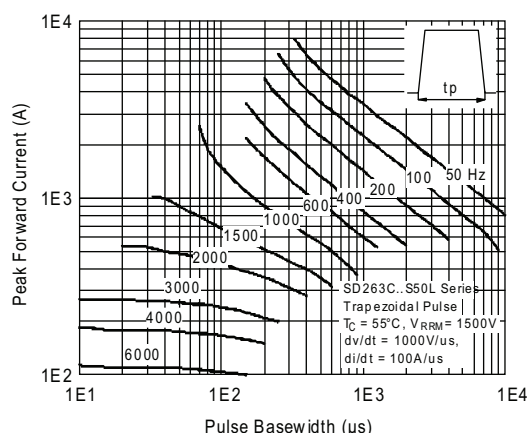


Fig. 20 - Frequency Characteristics

ORDERING INFORMATION TABLE

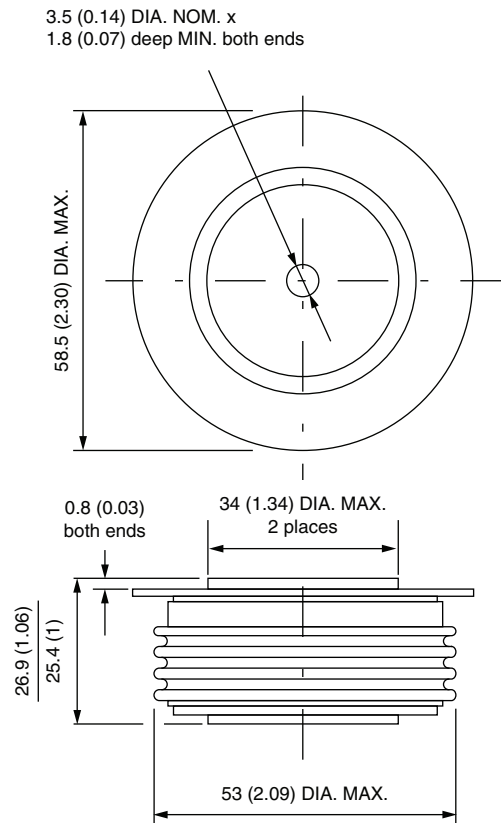
Device code	VS-	SD	26	3	C	45	S50	L
	①	②	③	④	⑤	⑥	⑦	⑧
1	-	Vishay Semiconductors product						
2	-	Diode						
3	-	Essential part number						
4	-	3 = Fast recovery						
5	-	C = Ceramic PUK						
6	-	Voltage code x 100 = V_{RRM} (see Voltage Ratings table)						
7	-	t_{rr} code						
8	-	L = PUK case DO-200AB (B-PUK)						

LINKS TO RELATED DOCUMENTS

Dimensions	www.vishay.com/doc?95246
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DO-200AB (B-PUK)

DIMENSIONS in millimeters (inches)



Quote between upper and lower pole pieces has to be considered after application of mounting force (see Thermal and Mechanical Specifications)



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